

Technical Information

4100 Gold Conductor

The thick film gold composition 4100 is a gold wire bondable conductor. Its high adhesion and good wire bonding capability make it suitable for most single and multilayer microcircuit applications. Key features include:

- High Conductivity
- Good Line Resolution
- High Wire Bond Adhesion
- Compatibility with Dielectrics and Resistors.

TYPICAL FIRED FILM CHARACTERISTICS⁽¹⁾

Fired Thickness	8-11 μ m
Line Resolution	175/125 μ m line/space using 150/150 μ m pattern and 325 mesh screen
Resistivity	≤ 5 m Ω / at 10 μ m fired thickness
Wire Bond Adhesion⁽²⁾	
Initial	≥ 9 grams
1000 Hours @ 150° C	≥ 8 grams

(1) Typical properties are based on testing of several batches under various processing conditions. They are not intended as specification limits.

(2) Thermosonic wire bonding of 1 mil gold wire on alumina substrate. All failures in the wire; no bond lifts.

COMPOSITION PROPERTIES

Viscosity:	300 \pm 20 Kcps, when measured with Brookfield HBT, Spindle #14, utility cup, 10 rpm, 25 C.
Specific Gravity:	5.3 - 5.8 g/cm ³
Recommended Thinner:	KOARTAN B-1194

RECOMMENDED PROCESSING PROCEDURE

Printing: Printing with 325 mesh stainless steel screen using 10-15 μm emulsion and 45 degree angle is recommended. Other mesh counts, 230-250, and emulsion thicknesses, 5-25 μm , may be used for special applications. Squeegee speeds of up to 6 inches/sec may be utilized.

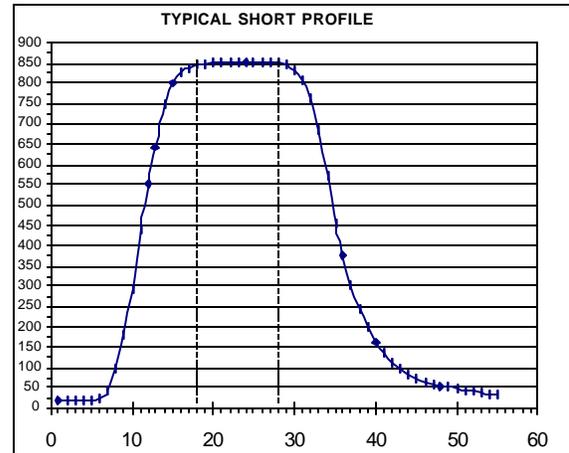
Coverage is approximately 60 cm^2 , when utilizing 325 mesh screen and a wet print thickness of about 35 μm .

Drying: Wet prints should be allowed to level for 5-10 minutes prior to drying. Dry for 10-15 minutes in a convection oven or belt dryer at 125°C-150°C.

Firing: Firing in air using a belt furnace and a 36-60 minute profile, with 10 minutes at a peak temperature of 850°C is recommended. Air flow rates must be optimized to ensure that the products of binder burn-off discharge properly and create a fully oxidizing atmosphere in the muffle.

Application Notes: If not handled properly, thick film gold conductors are prone to blistering. Circuits should be handled using gloves to avoid oily contamination from the fingertips. The rate of temperature rise during firing should not exceed 130°C/minute.

If the 4100 gold is printed on top a silver-bearing viafill conductor, without a barrier layer, the viafill must completely fill the via, and preferably extend slightly higher than the top of the dielectric.



Storage and Shelf Life: Store in tightly capped containers at room temperature. Shelf life is 6 months for unopened jars. Under ordinary conditions of storage and use the product should not require thinning. However, solvent loss during extended printing runs may be corrected by incorporating up to 0.5% of Koartan B-1194 thinner.

Other System Components:

Dielectric: 5807 (Gold & Mixed Metal)
5804 (Gold Only)

Inner Conductor 4100 (Gold)
6120 (Silver)

Via Fill: 4101 (Gold)
6101 (Ag)

Top Conductor 4225 (Al bondable Au)
4496 (Solderable Au)
6261 (Ag: Pd)

Resistor: 7600 Series

The information presented herein is based on data believed to be dependable and is accurate and reliable to the best of our knowledge and belief, but not guaranteed to be so. Koartan Company assumes no liability arising from the use of this product or the information provided herein. It is the responsibility of the user to verify the information and to establish the suitability of the product(s) for any particular application. Nothing herein is to be construed as recommending any practice or any product in violation of any patent or in violation of any law or regulation.